Vincotech

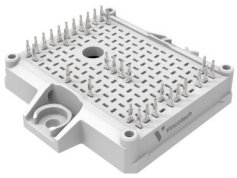
10-EY066PA100SA-L194F38T
datasheet

***flow*PACK E2** **600 V / 100 A**

Features

- Trench Fieldstop IGBT3 technology
- Standard industrial housing
- Optimized $R_{th(j-s)}$ with Phase Change Material
- Built-in NTC

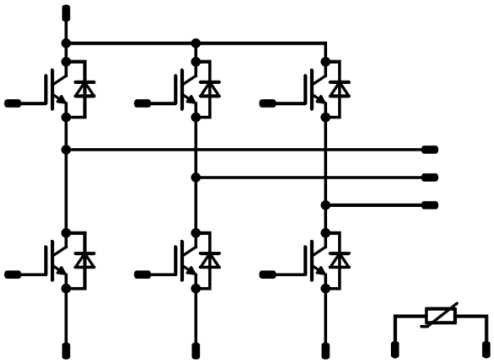
flow E2 12 mm housing



Target applications

- Industrial Drives

Schematic



Types

- 10-EY066PA100SA-L194F38T

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		600	V
Collector current	I_C	T_j = T_{jmax} T_s = 80 °C	88	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	300	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	152	W
Gate-emitter voltage	V_{GES}		±20	V
Short circuit ratings	t_{SC}	V_{GE} = 15 V Vcc = 360 V T_j = 150 °C	6	µs
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		600	V
Continuous (direct) forward current	I_F	T_j = T_{jmax} T_s = 80 °C	73	A
Repetitive peak forward current	I_{FRM}		300	A
Total power dissipation	P_{tot}	T_j = T_{jmax} T_s = 80 °C	107	W
Maximum junction temperature	T_{jmax}		175	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	6000	V
		AC Voltage t_p = 1 min	2500	V
Creepage distance			min. 12,7	mm
Clearance			9,08	mm
Comparative Tracking Index	CTI		≥ 600	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{GE} = V_{CE}$			0,0016	25	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CEsat}		15		100	25 125	1,05	1,57 1,75	1,85	V
Collector-emitter cut-off current	I_{CES}		0	600		25			5,1	µA
Gate-emitter leakage current	I_{GES}		20	0		25			600	nA
Internal gate resistance	r_g							2		Ω
Input capacitance	C_{ies}	f= 1 Mhz	25	20		25		6160		pF
Output capacitance	C_{oes}							384		
Reverse transfer capacitance	C_{res}							183		
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,62		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 2 Ω R_{goff} = 2 Ω	±15	350	100	25 125 150		104 107 108		ns
Rise time	t_r					25 125 150		20 23 24		
Turn-off delay time	$t_{d(off)}$					25 125 150		167 191 196		
Fall time	t_f					25 125 150		45 68 79		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 4,2 µC Q_{rFWD} = 8,2 µC Q_{rFWD} = 9 µC				25 125 150		1,698 2,734 3,009		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		2,422 3,297 3,485		

Characteristic Values

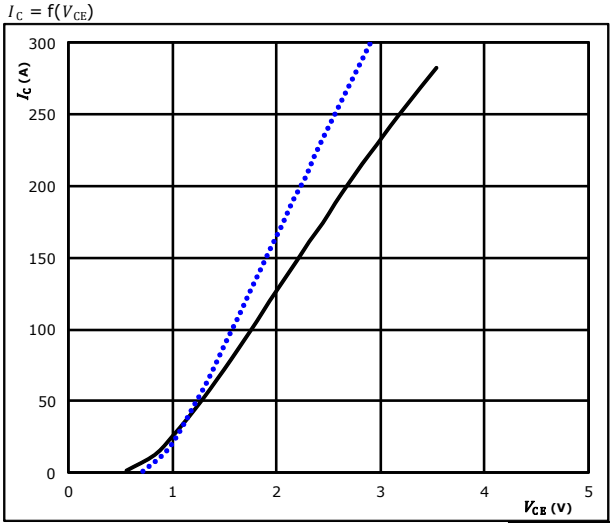
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				100	25 125	1,2	1,67 1,69	1,9	V
Reverse leakage current	I_R			600		25			660	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						0,88		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 5442 A/µs di/dt = 4043 A/µs di/dt = 3821 A/µs	±15	350	100	25 125 150		73 84 86		A
Reverse recovery time	t_{rr}					25 125 150		172 263 280		ns
Recovered charge	Q_r					25 125 150		4,151 8,189 8,993		µC
Reverse recovered energy	E_{rec}					25 125 150		1,009 1,962 2,123		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 125 150		4156 1829 1500		A/µs
Thermistor										
Rated resistance	R					25		5		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 493 Ω				100	-5		+5	%
Power dissipation	P					25		245		mW
Power dissipation constant						25		1,4		mW/K
B-value	$B_{(25/50)}$	Tol. ±2 %				25		3375		K
B-value	$B_{(25/100)}$	Tol. ±2 %				25		3437		K
Vincotech NTC Reference									K	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

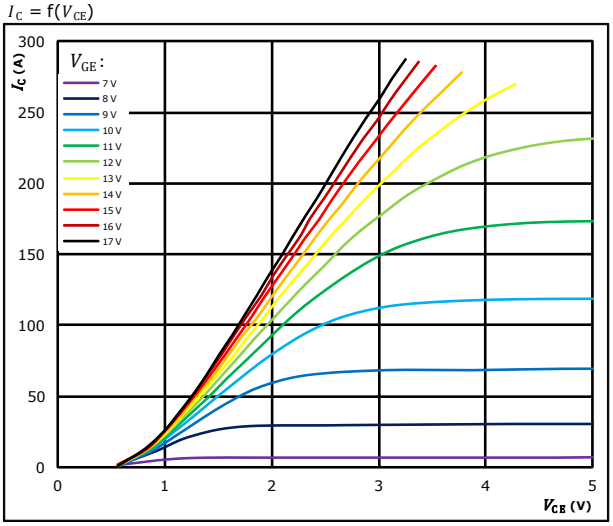


t_p =	250	µs	T_j:	25 °C	
V_{GE} =	15	V		125 °C	

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

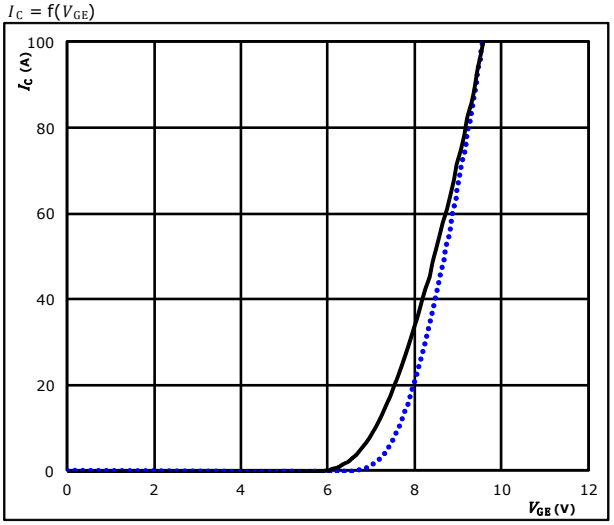


t_p =	250	µs
T_j =	125	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

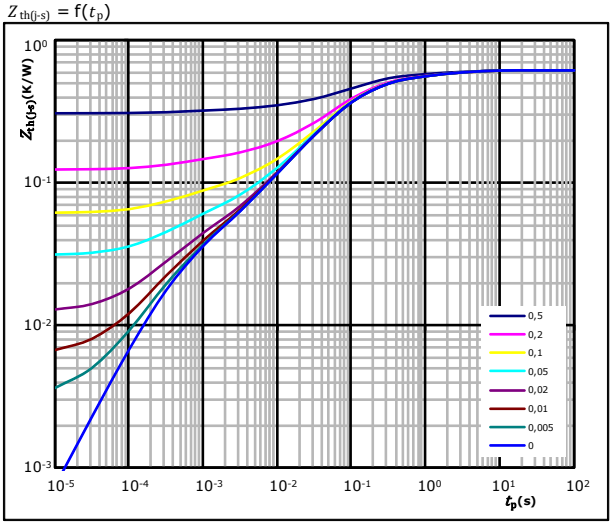


t_p =	100	µs	T_j:	25 °C	
V_{CE} =	10	V		125 °C	

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j-s)} = f(t_p)$



D =	t_p / T	
$R_{th(j-s)}$ =	0,62	K/W

IGBT thermal model values

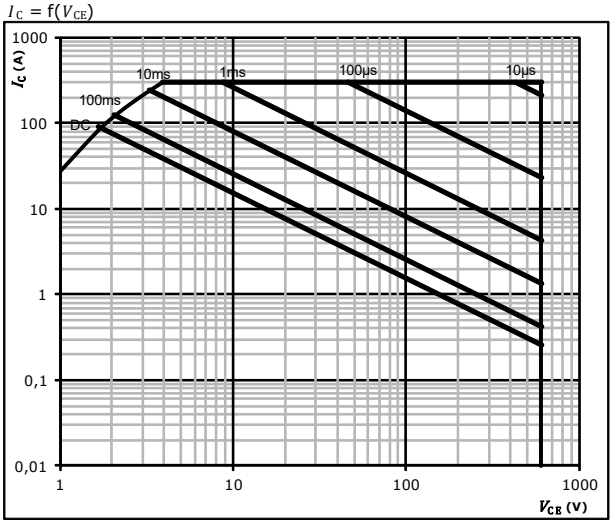
R (K/W)	τ (s)
6,37E-02	2,64E+00
1,09E-01	4,49E-01
3,30E-01	8,36E-02
7,06E-02	1,83E-02
2,75E-02	3,23E-03
2,32E-02	3,87E-04

Inverter Switch Characteristics

figure 5. **IGBT**

Safe operating area

$I_C = f(V_{CE})$



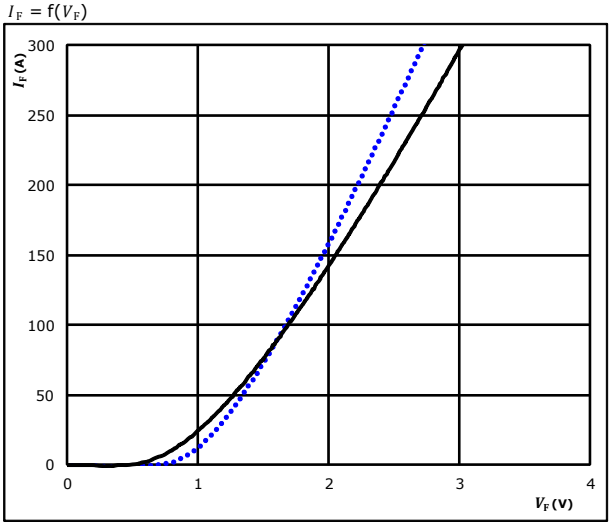
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



t_p = 250 µs

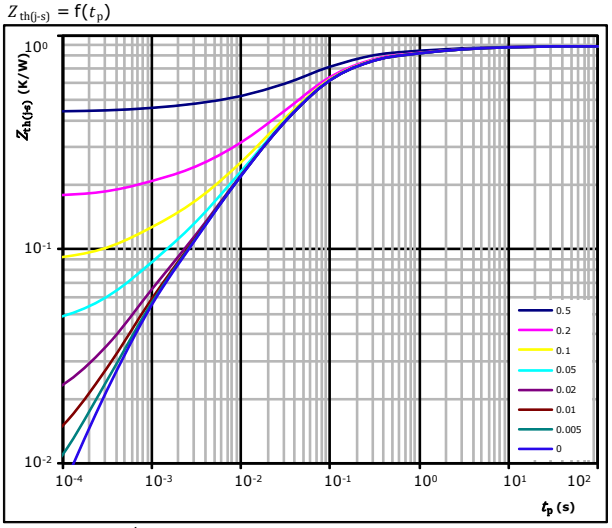
T_j: 25 °C

125 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



D = t_p / T

$R_{th(j-s)}$ = 0,88 K/W

FWD thermal model values

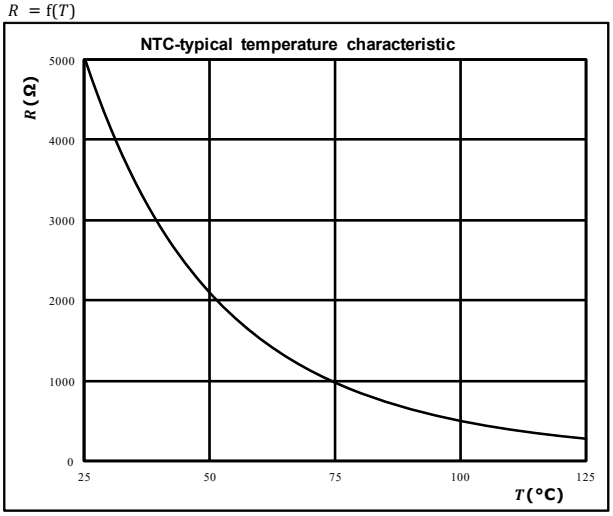
R (K/W)	τ (s)
3,86E-02	6,39E+00
8,37E-02	9,86E-01
2,73E-01	1,34E-01
3,45E-01	3,87E-02
1,03E-01	6,86E-03
4,12E-02	7,75E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic
as a function of temperature

$R = f(T)$

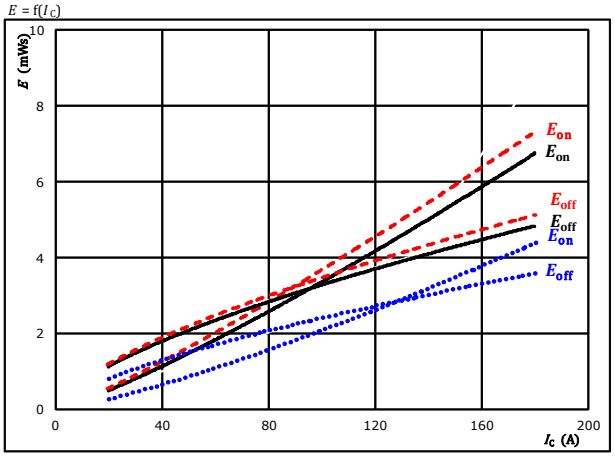


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



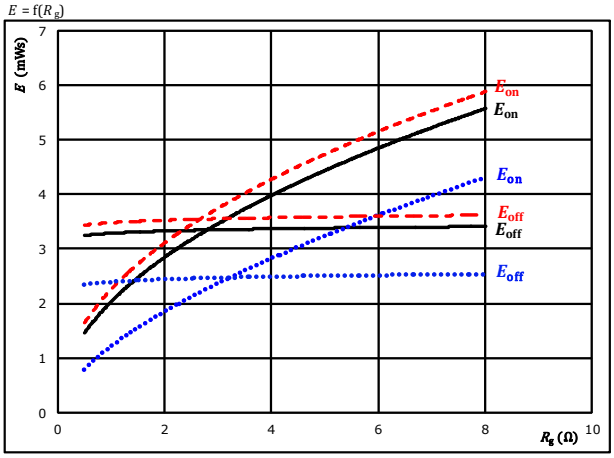
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C
R_{goff} =	2	Ω		

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



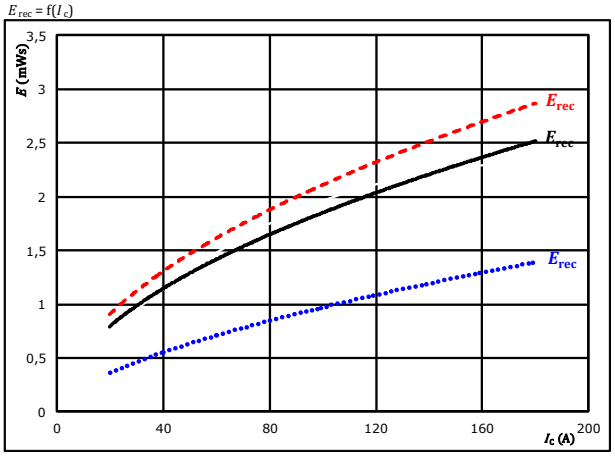
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



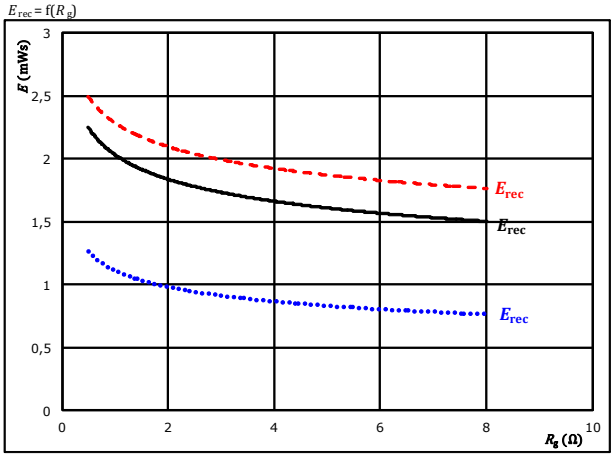
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at

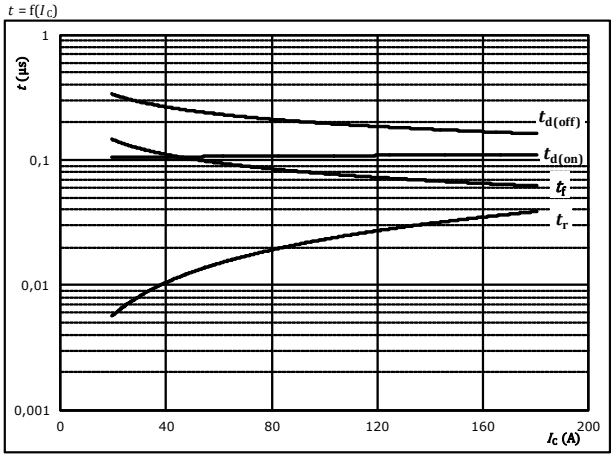
V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



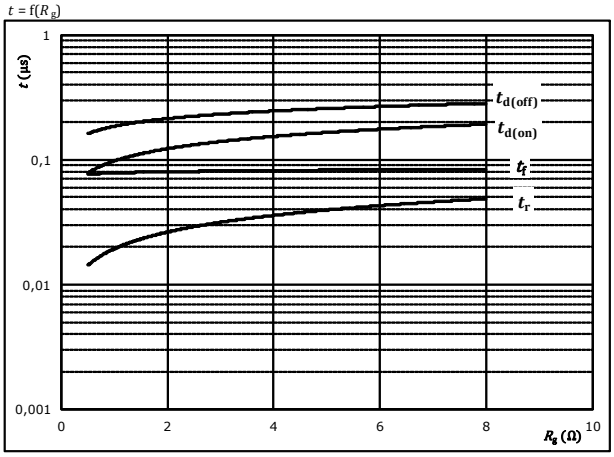
With an inductive load at

T_j =	150	°C
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	2	Ω
R_{goff} =	2	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



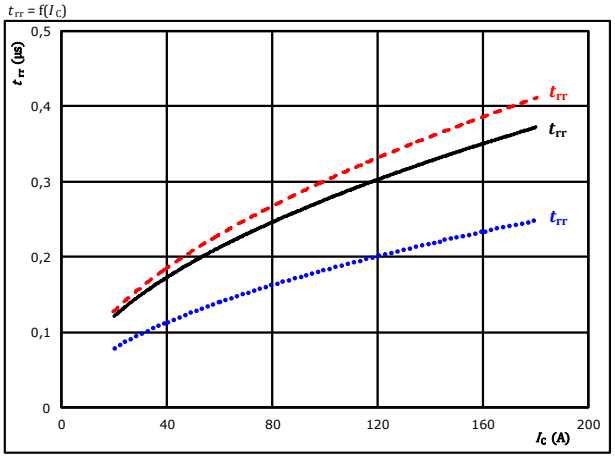
With an inductive load at

T_j =	150	°C
V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	100	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



With an inductive load at

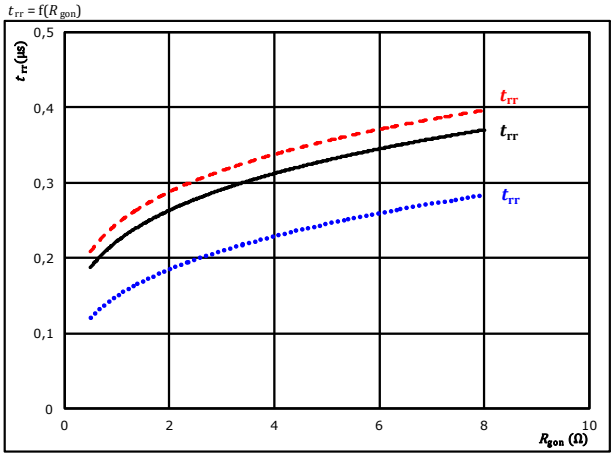
V_{CE} =	350	V
V_{GE} =	±15	V
R_{gon} =	2	Ω

T_j:	25 °C
	125 °C
	150 °C

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



With an inductive load at

V_{CE} =	350	V
V_{GE} =	±15	V
I_C =	100	A

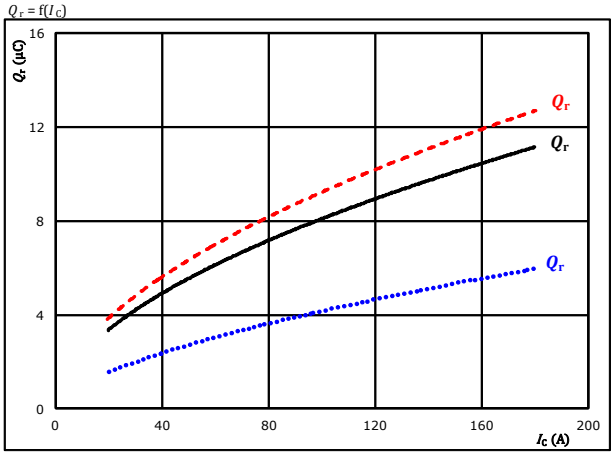
T_j:	25 °C
	125 °C
	150 °C

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$



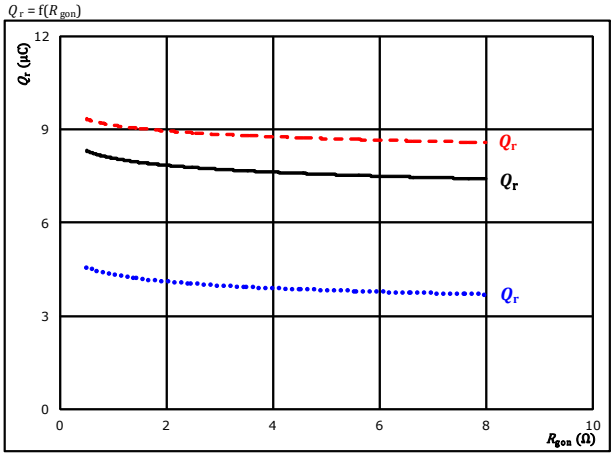
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 10. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$



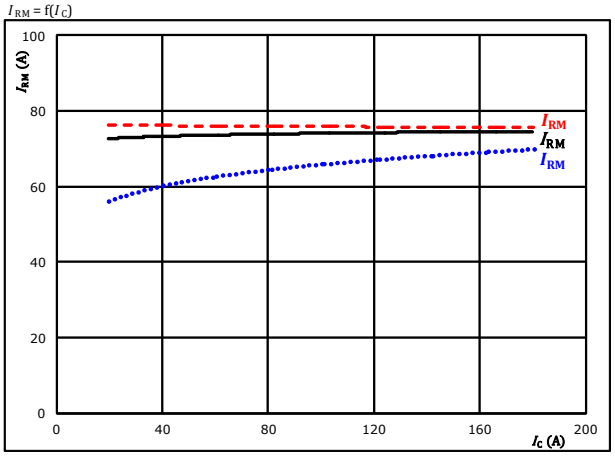
With an inductive load at

V_{CE}=	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C=	100	A		150 °C

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$



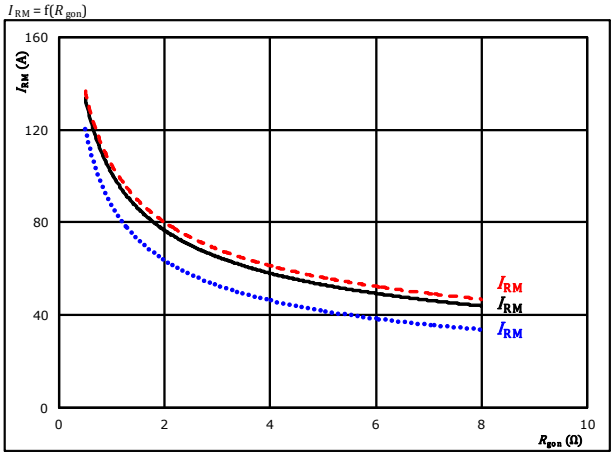
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



With an inductive load at

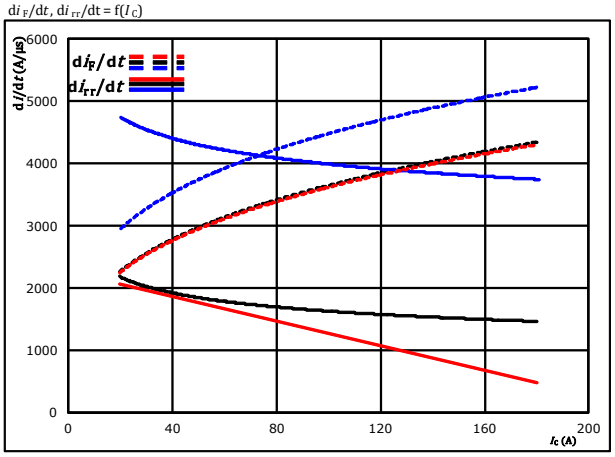
V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

di_F/dt, $di_{rr}/dt = f(I_C)$



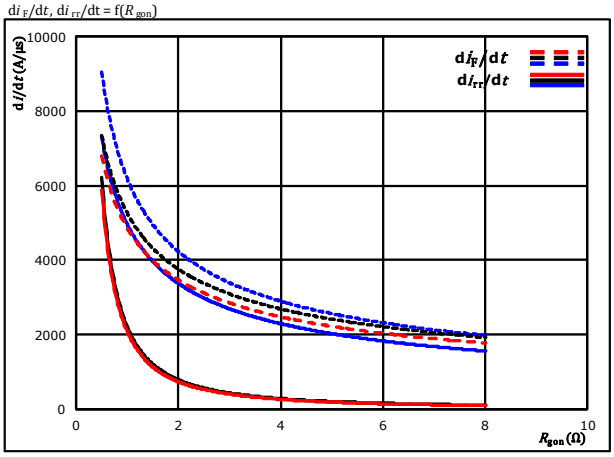
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
R_{gon} =	2	Ω		150 °C

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

di_F/dt, $di_{rr}/dt = f(R_{gon})$



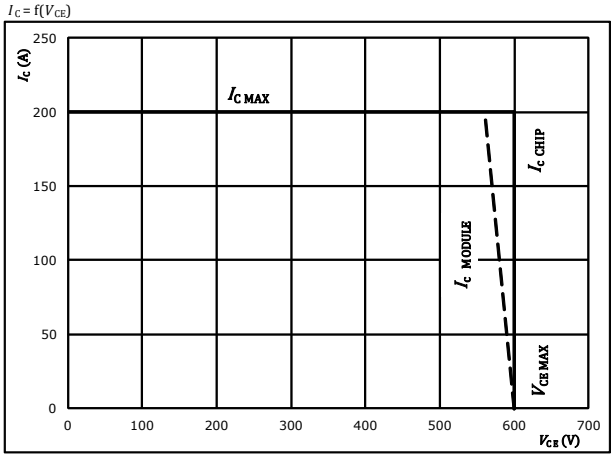
With an inductive load at

V_{CE} =	350	V	T_j:	25 °C
V_{GE} =	±15	V		125 °C
I_C =	100	A		150 °C

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j =	125	°C
R_{gon} =	2	Ω
R_{goff} =	2	Ω

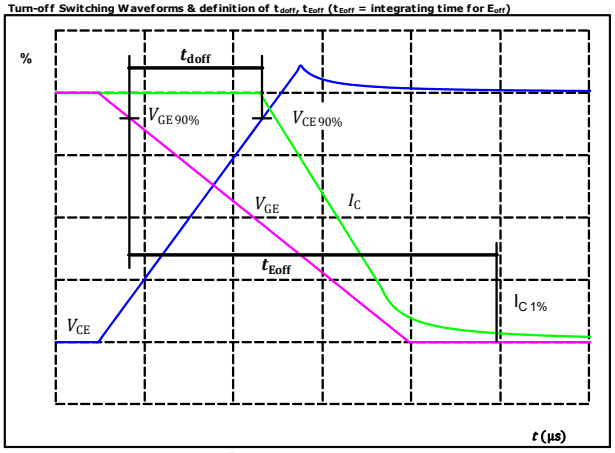
Inverter Switching Definitions

General conditions

T_j	=	125 °C
R_{gon}	=	2 Ω
R_{goff}	=	2 Ω

figure 1. IGBT

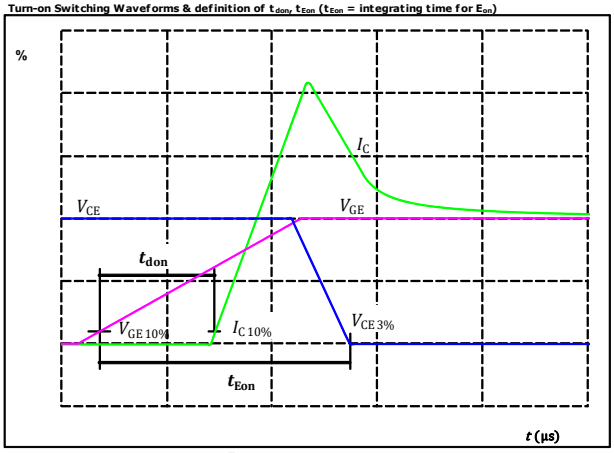
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	350	V
$I_C(100\%)$ =	100	A
t_{doff} =	191	ns

figure 2. IGBT

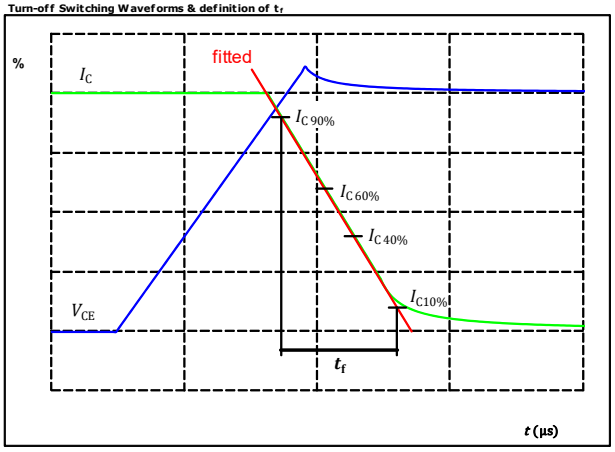
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	350	V
$I_C(100\%)$ =	100	A
t_{don} =	107	ns

figure 3. IGBT

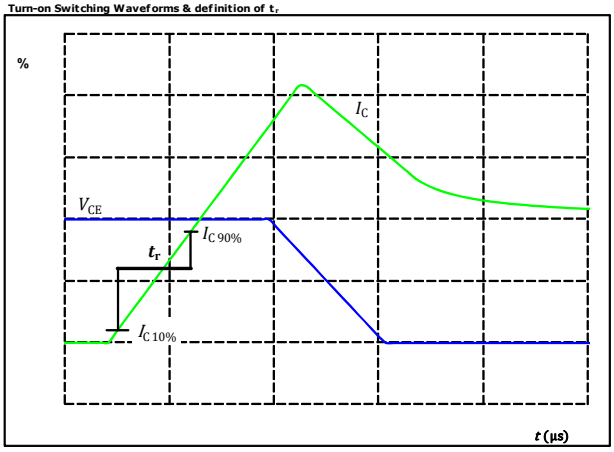
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	350	V
$I_C(100\%)$ =	100	A
t_f =	68	ns

figure 4. IGBT

Turn-on Switching Waveforms & definition of t_r

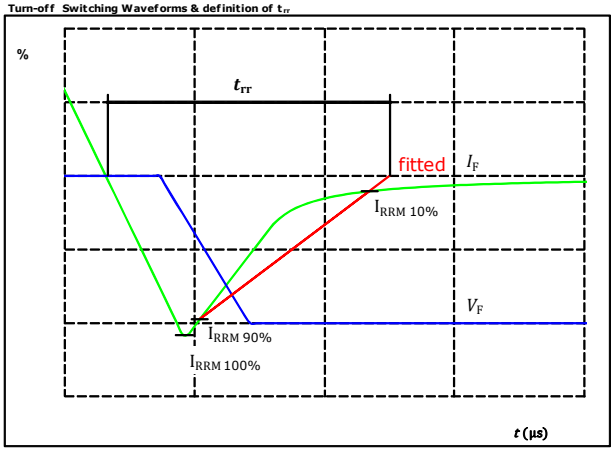


$V_C(100\%)$ =	350	V
$I_C(100\%)$ =	100	A
t_r =	23	ns

Inverter Switching Characteristics

figure 5. **FWD**

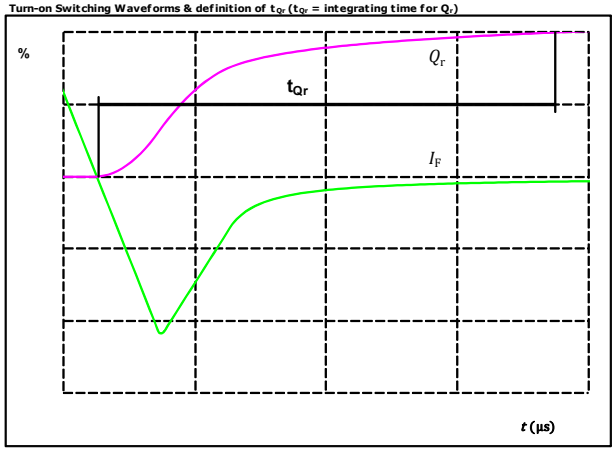
Turn-off Switching Waveforms & definition of t_{rr}



$V_F(100\%)$ =	350	V
$I_F(100\%)$ =	100	A
$I_{RRM}(100\%)$ =	84	A
t_{rr} =	263	ns

figure 6. **FWD**

Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



$I_F(100\%)$ =	100	A
$Q_r(100\%)$ =	8,19	µC

Vincotech

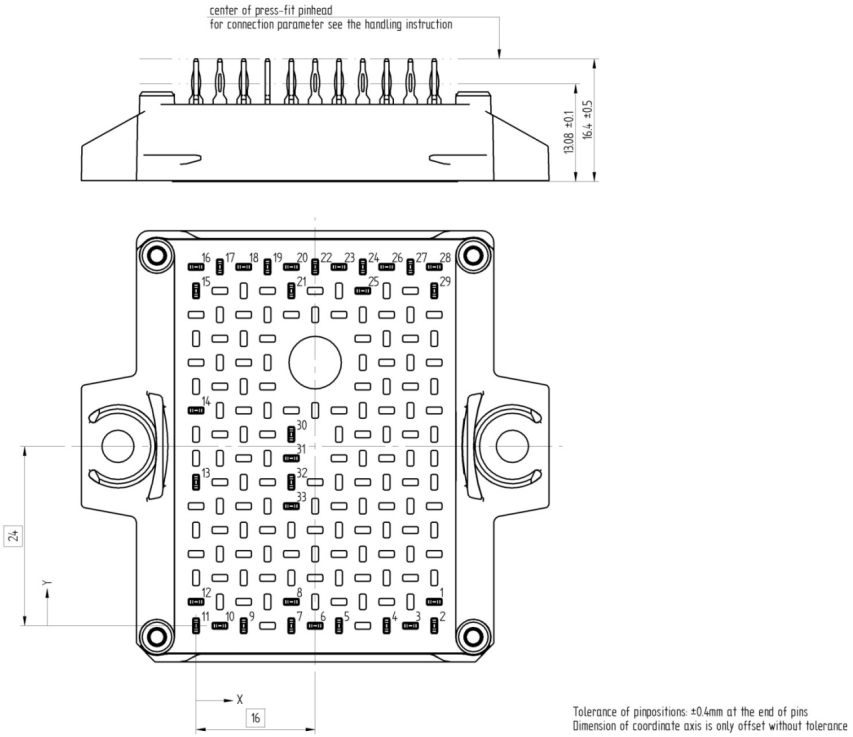
Ordering Code & Marking

Version	Ordering Code
without thermal paste 12 mm housing with Press-fit pins	10-EY066PA100SA-L194F38T
with thermal paste 12 mm housing with Press-fit pins	10-EY066PA100SA-L194F38T-/3/

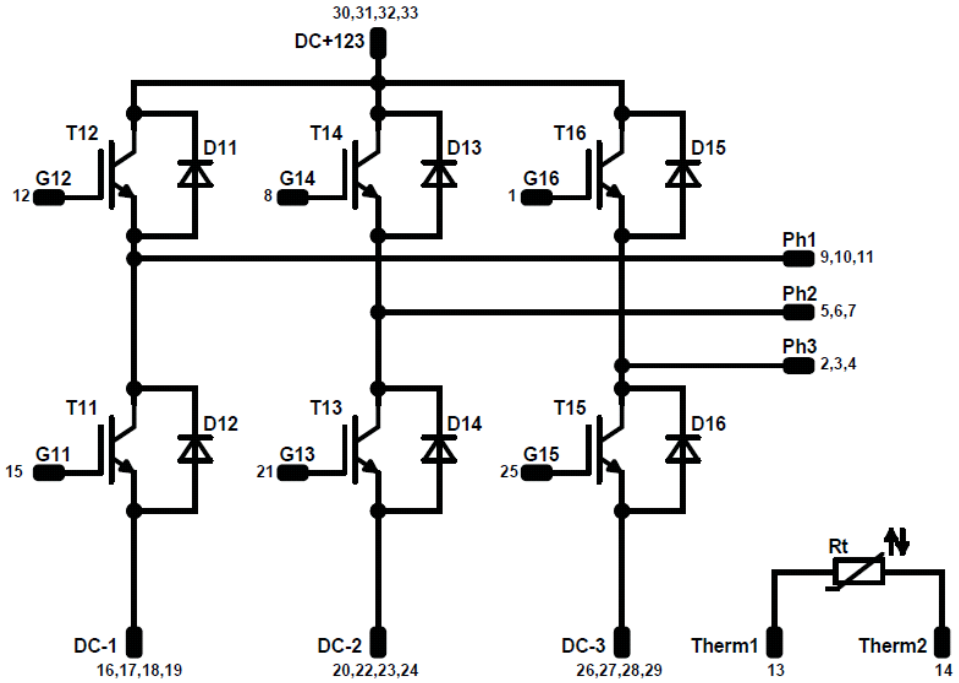
Text	Name		Date code	UL & VIN	Lot	Serial
	NN-NNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
Datamatrix	**Type&Ver**	**Lot number**	**Serial**	**Date code**		
	TTTTTTVV	LLLLL	SSSS	WWYY		

Outline

Pin table			
Pin	X	Y	Function
1	32	3,2	G16
2	32	0	Ph3
3	28,8	0	Ph3
4	25,6	0	Ph3
5	19,2	0	Ph2
6	16	0	Ph2
7	12,8	0	Ph2
8	12,8	3,2	G14
9	6,4	0	Ph1
10	3,2	0	Ph1
11	0	0	Ph1
12	0	3,2	G12
13	0	19,2	Therm1
14	0	28,8	Therm2
15	0	44,8	G11
16	0	48	DC-1
17	3,2	48	DC-1
18	6,4	48	DC-1
19	9,6	48	DC-1
20	12,8	48	DC-2
21	12,8	44,8	G13
22	16	48	DC-2
23	19,2	48	DC-2
24	22,4	48	DC-2
25	22,4	44,8	G15
26	25,6	48	DC-3
27	28,8	48	DC-3
28	32	48	DC-3
29	32	44,8	DC-3
30	12,8	25,6	DC+
31	12,8	22,4	DC+
32	12,8	19,2	DC+
33	12,8	16	DC+



Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	600 V	100 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	600 V	100 A	Inverter Diode	
Rt	NTC			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* E2 packages see vincotech.com website.

Package data
Package data for *flow* E2 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-EY066PA100SA-L194F38T-D1-14	23 Aug. 2018		